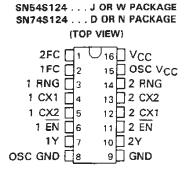
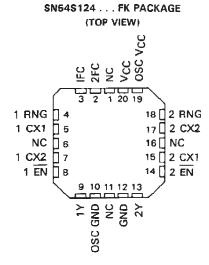
- Two independent VCOs in a 16-Pin Package
- Output Frequency Set by Single External Component:
 - Capacitor for Fixed- or Variable-Frequency Operation
- Separate Supply Voltage Pins for Isolation of Frequency Control Inputs and Oscillators from Output Circuitry
- Highly Stable Operation over Specified Temperature and/or Supply Voltage Ranges
- Typical f_{max} 85 MHz
 Typical Power Dissipation 525 mW
- Frequency Spectrum . . . 1 Hz to 60 MHz

description

The 'S124 features two independent voltage-controlled oscilllators (VCO) in a single monolithic chip. The output frequency of each VCO is established by an external capacitor in combination with two voltage-sensitive inputs, one for frequency range and one for frequency control. These inputs can be used to vary the output frequency as shown under typical characteristics. These highly stable oscillators can be set to operate at any frequency typically between 0.12 hertz and 85 megahertz.





NC - No internal connection

While the enable input is low, the output is enabled. While the enable input is high, the output is high,

These devices can operate from a single 5-volt supply. However, one set of supply-voltage and ground pins (V_{CC} and GND) is provided for the enable, synchronization-gating, and output sections, and a separate set (O_{CC} and O_{CC}

The enable input of these devices starts or stops the output pulses when it is low or high, respectively. The internal oscillator of the 'S124 is started and stopped by the enable input. The enable input is one standard load; it and the buffered output operate at standard Schottky-clamped TTL levels.

The pulse synchronization-gating section ensures that the first output pulse is neither clipped nor extended. Duty cycle of the square-wave output is fixed at approximately 50 percent.

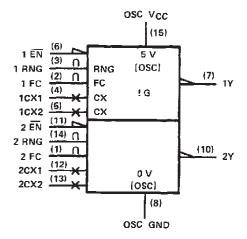
The SN54S124 is characterized for operation over the full military temperature range of -55° C to 125°C; the SN74S124 is characterized for operation from 0°C to 70°C.



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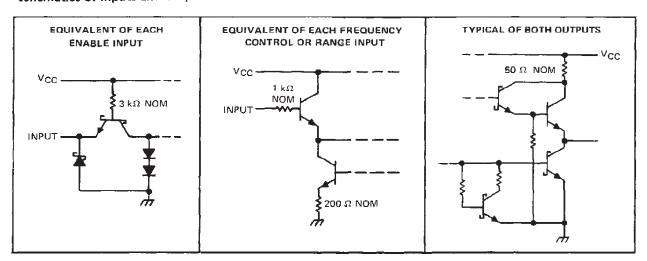
logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (See Notes 1 and 2)	7V
Input voltage	5.5 V
Operating free-air temperature range: \$N54\$124	–55°C to 125°C
SN74S124	0°C to 70°C
Storage temperature range	–65°C to 150°C

NOTES: 1. Voltage values are with respect to the appropriate ground terminal.

2. Throughout this data sheet, the symbol VCC is used for the voltage applied to both the VCC and OVCC terminals, unless other wise noted.



recommended operating conditions

	SN54S124		SN74S124				
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC} (see Note 1)	4.5	5	5.5	4.75	5	6.25	٧
Input voltage at frequency control or range input, VI(freq) or VI(rng)	1		5	1		5	V
High-level output current, IOH			-1			-1	mA
Low-level output current, IOL			20			20	mA
Output frequency (enabled), fo	1			1			Hz
Output frequency tenabledr, 10			60			60	MHz
Operating free-air temperature, TA	-55		125	0	<u> </u>	70	"C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†			MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage at enat				2			V	
ViL	V _{1L} Low-level input voltage at enable					†		0.8	V
VΙΚ	VIK Input clamp voltage at enable		V _{CC} = MIN,	I _I = -18 mA				-1.2	V
V	High level gutout voltage		VCC = MIN, VIH = 21		SN54S'	2.5	3.4		V
AOH	VOH High-level output voltage		1 _{OH} = -1 mA		SN 745'	2.7	3.4		V
VOL Low-level output voltage			V _{CC} = MIN, V _{JL} = 0.8 V,					0.5	v
1.	Input ductors	Freq control	W	V1 - 5 V		10	50		
1 į	I Input current or range		V _{CC} = MAX	V _I = 1 V		1	15	μА	
4	Input current at maximum input voltage	Enable	V _{CC} = MAX, V ₁ = 5.5 V				1	mA	
ΉΗ	High-level input current	Enable	V _{CC} = MAX, V ₁ = 2.7 V				50	μА	
IIL	Low-level input current	Enable	V _{CC} = MAX, V _I = 0.5 V		1		-2	mA	
los	Short-circuit output current §		V _{CC} = MAX		-40		-100	mΑ	
			VCC = MAX, S	See Note 3			105	150	
Supply current, total into VCC and VCC		V _{CC} = MAX, 1 See Note 3	r _A = 125°C,	W package only		_	110	mA	

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡All typical values are at $V_{CC} \approx 5 \, \text{V}$. $T_A = 25 \, \text{°C}$. 5 Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. NOTE 3: I_{CC} is measured with the outputs disabled and open.

switching characteristics, V_{CC} = 5 V, R_L = 280 Ω , C_L = 15 pF, T_A = 25°C (see note 4)

	PARAMETER TEST CONDITIONS			TYP N	XAN	UNIT
fo	Output frequency	C = 2 pE V (freq) = 4 V, V (rng) = 1 V	60	85		MHz
10 Output frequency	C _{ext} = 2 pF Vi(freq) = 1 V, Vi(rng) = 5 V	25	40			
	Output duty cycle	C _{ext} = 8.3 pF to 500 µF		50%		
Propagation delay time, TPHL high-to-low-level output from enable		f ₀ = 1 Hz to 20 MHz		1.4 fo(Hzl		s
	mgn-to-low-lever output from enable	f _o > 20 MHz		70		ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL CHARACTERISTICS

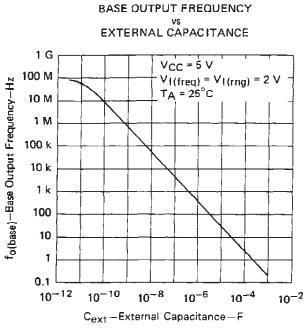


FIGURE 1

NOTE: $f_0 = f_n \times f_0(base)$

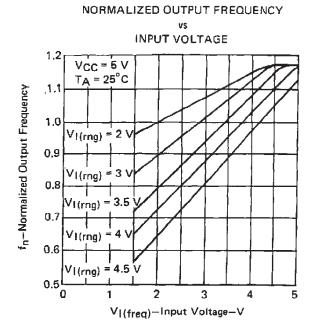


FIGURE 2





ti.com 28-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN54S124J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SN74S124D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S124DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S124N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S124N3	OBSOLETE	PDIP	N	16		None	Call TI	Call TI
SNJ54S124J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SNJ54S124W	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

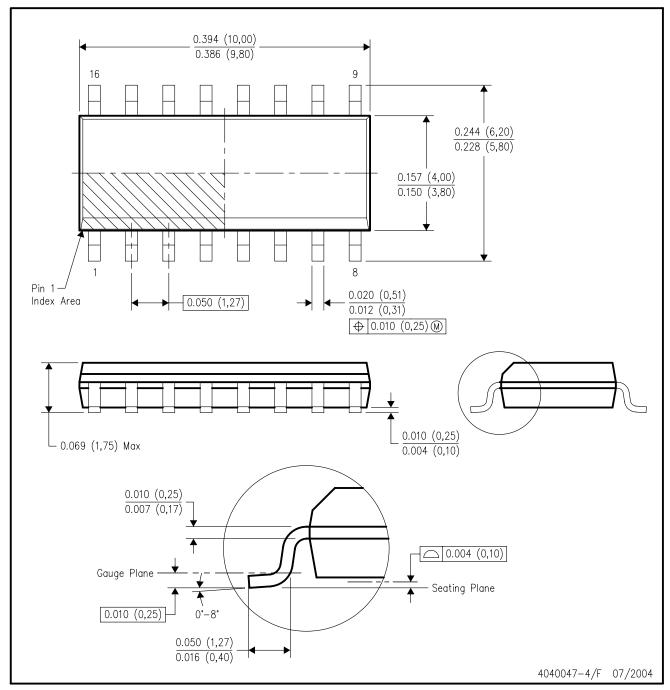


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



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